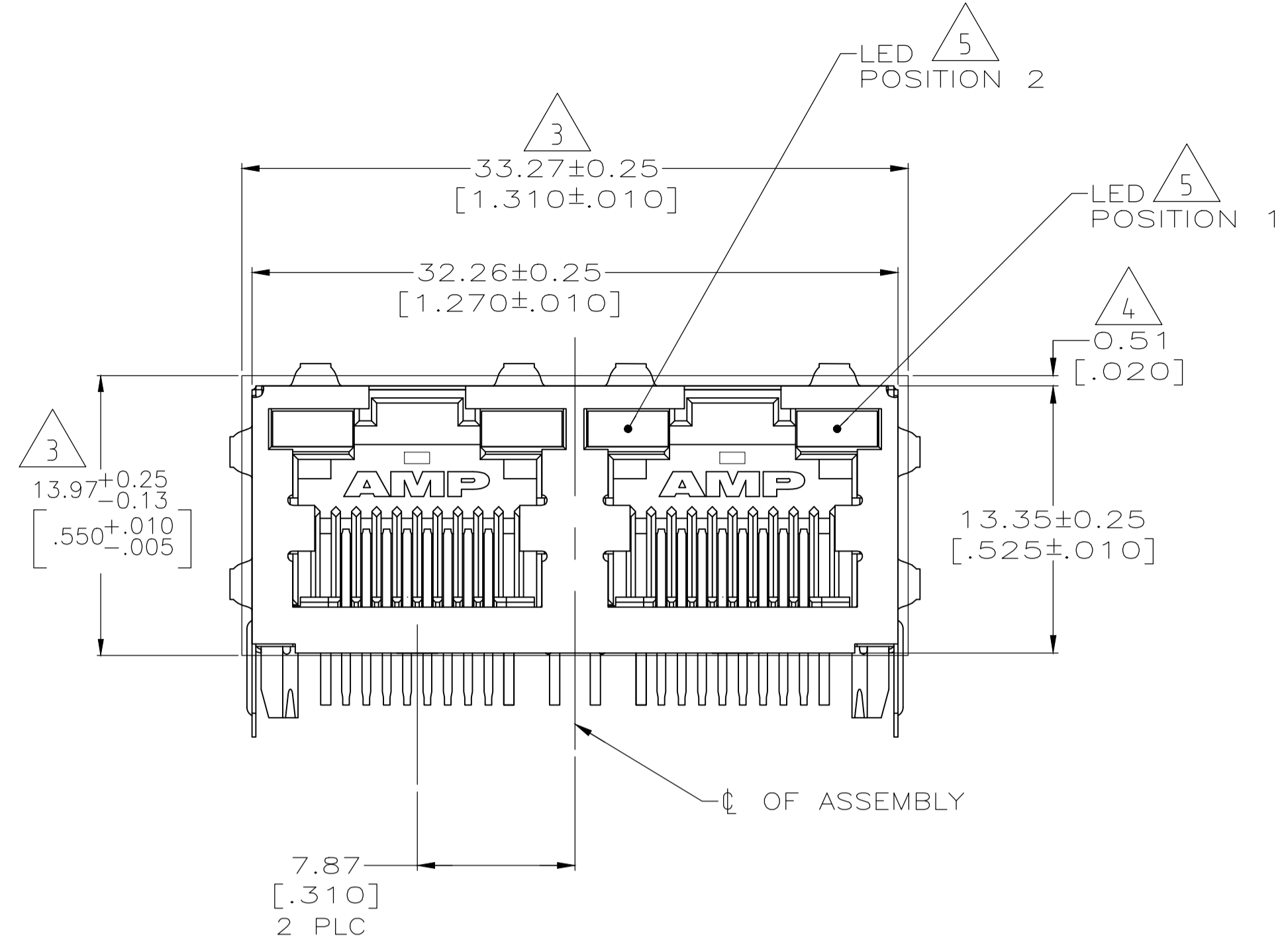
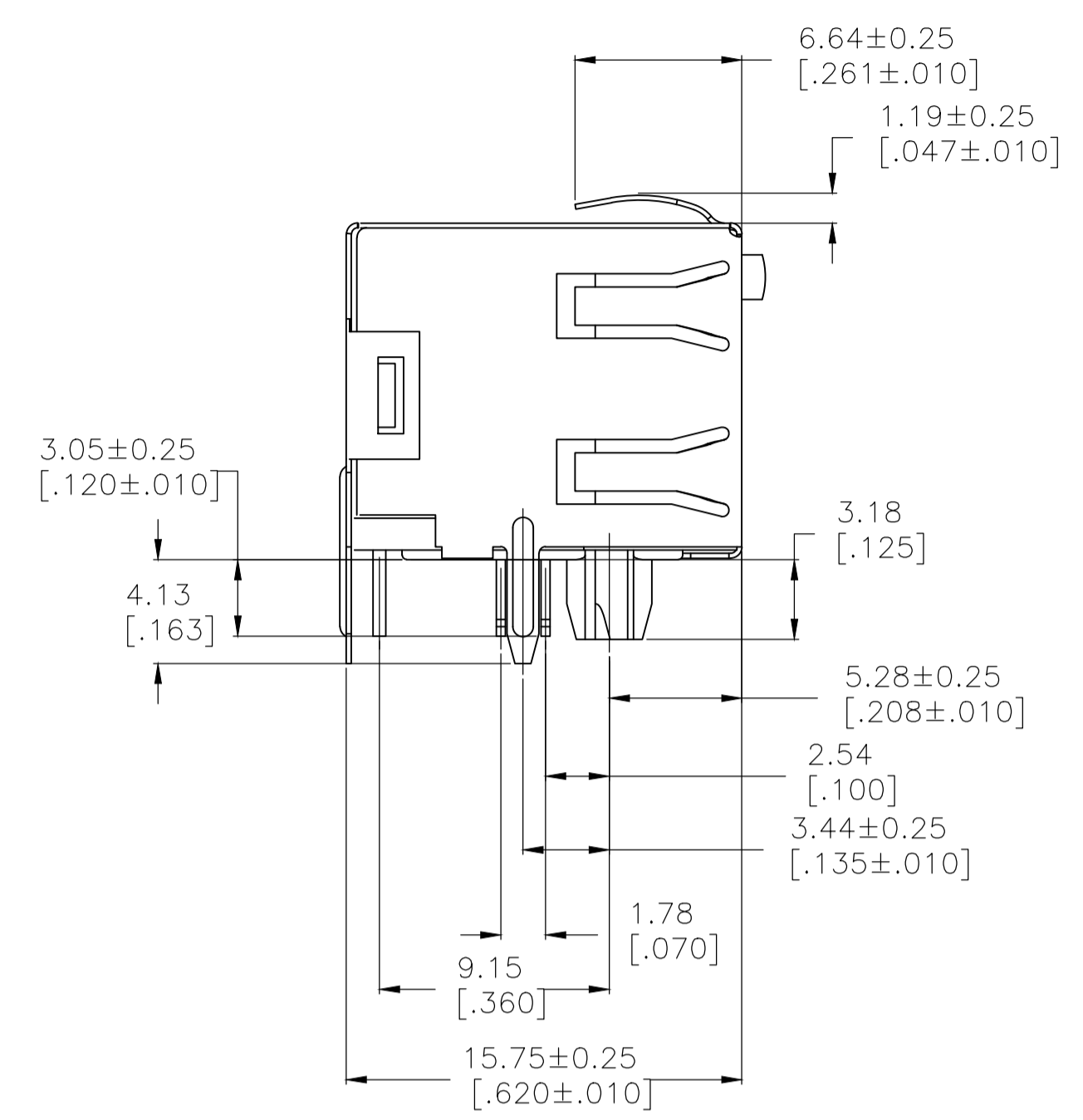
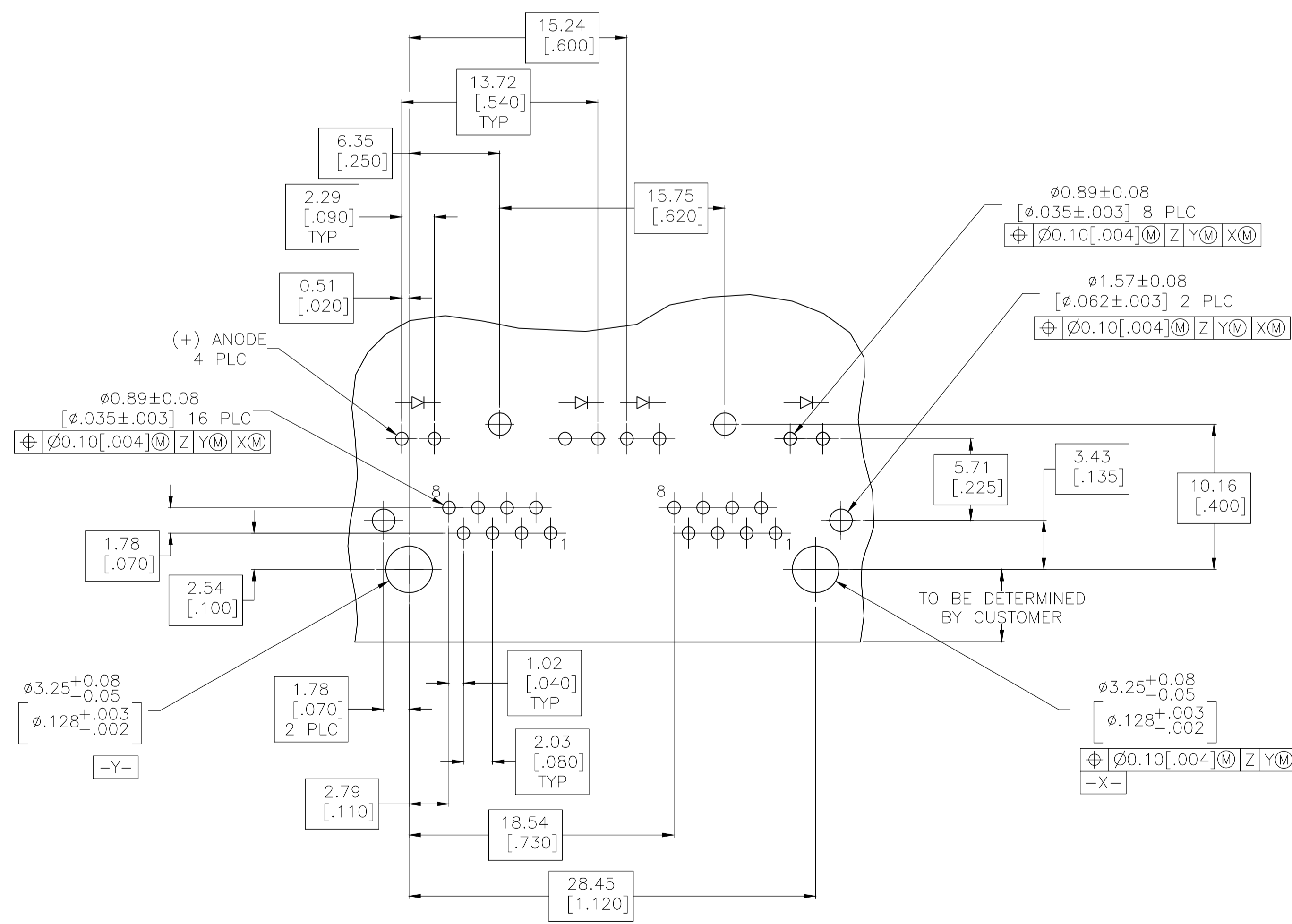


REVISIONS					
P	LTR	DESCRIPTION	DATE	DMN	APVD
B		ECC-18-014918	13JULY2018	RR	SH



- MATERIAL:
 HOUSING - HIGH TEMPERATURE THERMOPLASTIC, COLOR: BLACK, UL94V-0
 TERMINALS - 0.36[.014] THICK PHOS BRONZE PLATED WITH 3.81µm[.000150] MIN THICK BRIGHT TIN LEAD IN SOLDER AREA, 1.27µm[.000050] MIN GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27µm[.000050] MIN THICK NICKEL.
 SHIELD - 0.196[.0077] THICK COPPER ZINC ALLOY PREPLATED WITH 1.27µm[.000050] MIN SATIN NICKEL WITH 2.03µm[.000080] MIN TIN POST DIPPED ON PCB GROUND TABS
 LIGHT EMITTING DIODE (LED) - DIFFUSED EPOXY LENS, 0.51 X 0.51[.020 X .020] CARBON STEEL WIREFRAME LEADS PLATED WITH 8.89µm[.000350] TIN/COPPER OVER 2.03µm[.000080] SILVER OVER 1.02µm[.000040] NICKEL UNDERPLATE OVER 2.03µm[.000080] COPPER UNDERPLATE
- JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- SUGGESTED PANEL OPENING DIMENSIONS.
- SUGGESTED CLEARANCE BETWEEN TOP OF CONNECTOR AND TOP PANEL OPENING.
- SEE TABLE FOR COLOR OF LEDS AND NUMBER REQUIRED.
- THIS MODULAR JACK WITH INTEGRATED LED IS NOT IR REFLOW SOLDERING PROCESS COMPATIBLE.



RECOMMENDED PC BOARD LAYOUT COMPONENT SIDE

OBSOLETE	GREEN	YELLOW	1368460-4
	POSITION 2	POSITION 1	PART NUMBER
INDICATOR COLOR FOR EACH HOUSING			

THIS DRAWING IS A CONTROLLED DOCUMENT.		DMN DL DRUMMOND 23SEP2003	TE Connectivity	
DIMENSIONS: mm [INCHES]		CHK EC LAURER 23SEP2003	INVERTED MODULAR JACK ASSEMBLY, 1X2, SHIELDED, PANEL GROUND WITH LEDS	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD EC LAURER 23SEP2003	NAME	
0 PLC ± -	1 PLC ± -	PRODUCT SPEC 108-1163-4		
2 PLC ± 0.25(.01)	3 PLC ± 0.13(.005)	APPLICATION SPEC 114-2154		
4 PLC ± -	ANGLES ± -	SIZE CAGE CODE DRAWING NO RESTRICTED TO		
MATERIAL SEE NOTE 1	FINISH SEE NOTE 1	WEIGHT 0.000000	A1 00779	SCALE 4:1 SHEET 1 OF 1 REV B
CUSTOMER DRAWING		1368460		